

# SBM1040

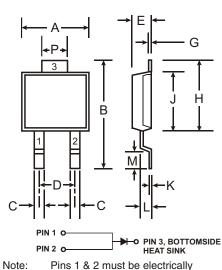
## 10A LOW VF SCHOTTKY BARRIER RECTIFIER POWERMITE®3

## Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Max Junction Temperature Rating
- Low Forward Voltage Drop
- Very Low Leakage Current
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications

## **Mechanical Data**

- Case: POWERMITE®3, Molded Plastic
- Plastic Material: UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.072 grams (approx.)
- Marking information: See sheet 3



POWERMITE®3			
Dim	Min	Max	
Α	4.03	4.09	
В	6.40	6.61	
С	.864	.914	
D	1.83 NOM		
E	1.10	1.14	
G	.173	.203	
н	5.01	5.17	
J	4.37	4.43	
К	.173	.203	
L	.71	.77	
М	.36	.46	
Р	1.73	1.83	
All Dimensions in mm			

Pins 1 & 2 must be electrically connected at the printed circuit board.

#### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit V	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V	
Average Rectified Output Current (see also Figure 4)	lo	10	А	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method) $@T_C = 88^{\circ}C$	I <sub>FSM</sub>	150	A	
Typical Thermal Resistance Junction to Soldering Point	$R_{ hetaJS}$	2.5	°C/W	
Operating Temperature Range	Tj	-65 to +150	°C	
Storage Temperature Range	T <sub>STG</sub>	-65 to +150	°C	

## Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

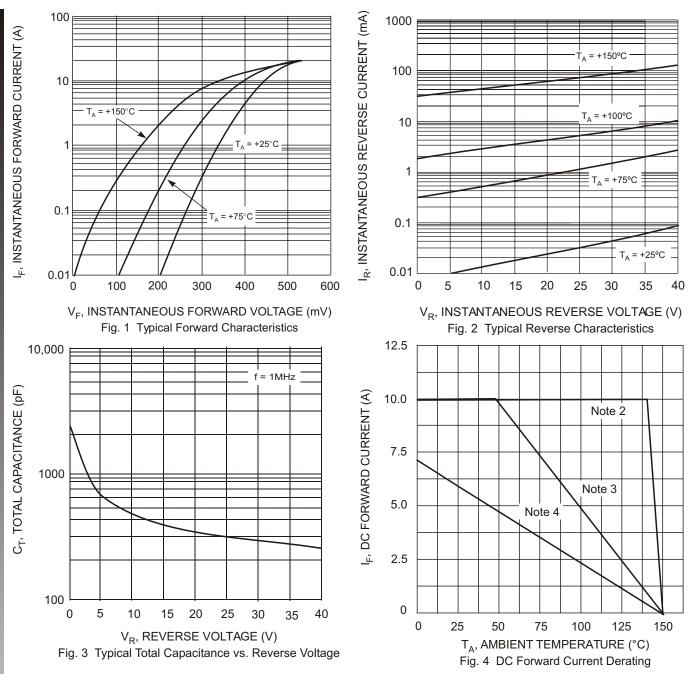
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V <sub>(BR)R</sub>	40	_	_	V	I <sub>R</sub> = 1mA
Forward Voltage (Note 1)	VF		0.45  0.47	0.49 0.41 0.51	V	$    I_F = 8A, T_S = 25^{\circ}C \\    I_F = 8A, T_S = 125^{\circ}C \\    I_F = 10A, T_S = 25^{\circ}C $
Reverse Current (Note 1)	IR	_	0.1 12.5	0.3 25	mA	$ \begin{array}{l} T_{S} = & 25^{\circ}C,  V_{R} = 35V \\ T_{S} = & 100^{\circ}C,  V_{R} = 35V \end{array} $
Total Capacitance	CT		700		pF	f = 1.0MHz, V <sub>R</sub> = 4.0V DC

Notes: 1. Short duration test pulse used to minimize self-heating effect.

DS30255 Rev. 9 - 2



**NEW PRODU** 



Notes: 2.  $T_A = T_{SOLDERING POINT}$ ,  $R_{\theta JS} = 2.5^{\circ}C/W$ ,  $R_{\theta SA} = 0^{\circ}C/W$ .

Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". R<sub>0JA</sub> in range of 15-30°C/W.

 Device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. R<sub>0JA</sub> in range of 60-75°C/W.



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Notes:

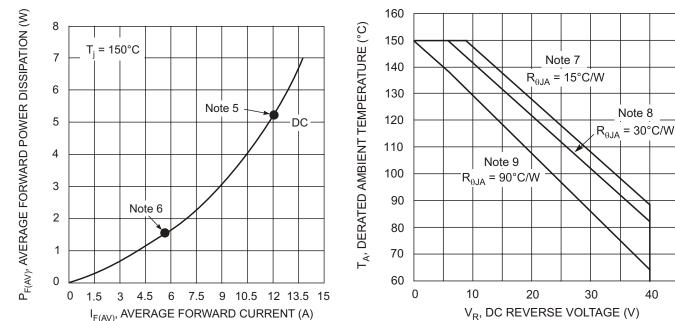


Fig. 6 Operating Temperature Derating

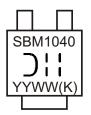
- Maximum power dissipation when device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". R<sub>θJA</sub> in range of 15-30°C/W.
  - Maximum power dissipation when device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. R<sub>θJA</sub> in range of 60-75°C/W.
  - R<sub>0JA</sub> = 15°C/W when mounted on 2"x2", single-sided, ceramic board with cathode pad dimensions 0.75"x1.0", anode pad dimensions 0.25"x1.0".
  - R<sub>0JA</sub> = 30°C/W when mounted on 2"x2", single-sided, FR-4 board with cathode pad dimensions 0.5"x1.0", anode pad dimensions 0.5"x1.0", 2 oz. copper pads.
  - 9. R<sub>0JA</sub> = 90°C/W when mounted on 0.5"x0.625", single-sided, FR-4 board with minimum recommended pad layout.

#### Ordering Information (Note 10)

Device	Packaging	Shipping
SBM1040-13	POWERMITE®3	5000/Tape & Reel

Notes: 10. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**



SBM1040 = Product type marking code ):: = Manufacturers' code marking YYWW = Date code marking YY = Last two digits of year ex: 02 for 2002 WW = Week code 01 to 52 (K) = Factory designator

Fig. 5 Forward Power Dissipation

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